

Felt-based Polishing Pad

SUBA™

SUBA™ pad is foamed by non-woven felt which polyurethane is coagulated. SUBA™ shows excellent performance at stock polishing in silicon wafer, sapphire wafer and oxide material wafer.

SUBA™ Series

SUBA™ pad is designed for stock removal and semi-final process of silicon wafer polishing. Also, it's available for the edge and notch polishing of silicon wafer. There are many product lines to cover each process requirement.

▣ Advantages

1. High removal rate
2. Low defectivity
3. Excellent flatness



▣ SEM Image



SUBA400



SUBA600



SUBA800

▣ Physical Properties

Product	Thickness (mm)	Hardness (Asker C)	Compressibility (%)
SUBA™ 400	1.27	60	9.4
SUBA™ 600	1.27	80	4.2
SUBA™ 800	1.27	83	3.3
SUBA™ 840	1.27	84	2.6
SUBA™ 800M2	1.27	87	2.7

※ SUBA™ is a trademark, service mark or registered trademark of affiliates of DuPont de Nemours, Inc.

※ The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.